Docket No.: 3273-0208PUS1

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Hisashi MAESHIMA, et al.

Application No.: 10/526,672

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Filed: March 4, 2005

For: PROCESS FOR PREPARATION OF
ALICYCLIC DIEPOXY COMPOUNDS,
CURABLE EPOXY RESIN COMPOSITIONS,
EPOXY RESIN COMPOSITIONS FOR THE
ENCAPSULATION OF ELECTRONIC PARTS,
STABILIZERS FOR ELECTRICAL
INSULATING OILS, AND CASTING EPOXY

RESIN COMPOSITIONS FOR ELECTRICAL INSULATION

Confirmation No.: 3246

Art Unit: 1796

Examiner: Robert SELLERS

Do not enter.

/Robert Sellers/

7/25/2008

AMENDMENT UNDER 37 CFR 1.116

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In reply to the Office Action dated April 23, 2008, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes:

Amended Claim Set; and

Remarks.